

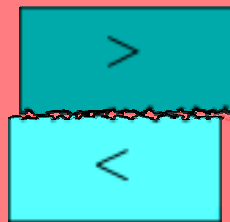
# Properties of Additives Molecules for Boundary Lubrication

**S.K. Biswas**

**Department of Mechanical Engineering  
Materials Research Centre  
Indian Institute of Science  
Bangalore, India**

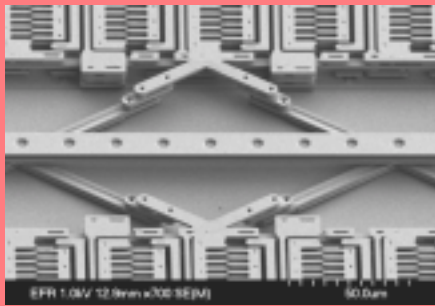


**TRIBOLOGY**





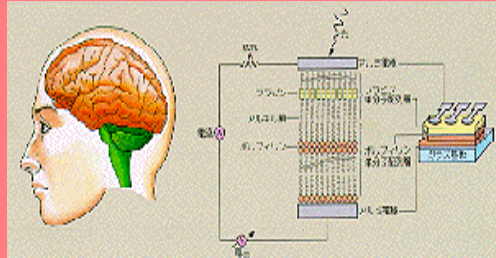
## HUMAN JOINT



## MEMS

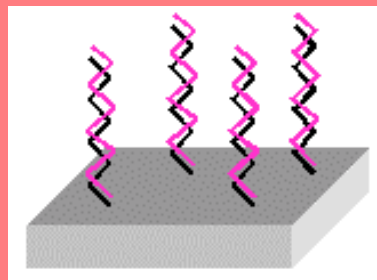


## DIAGNOSING AND SENSING

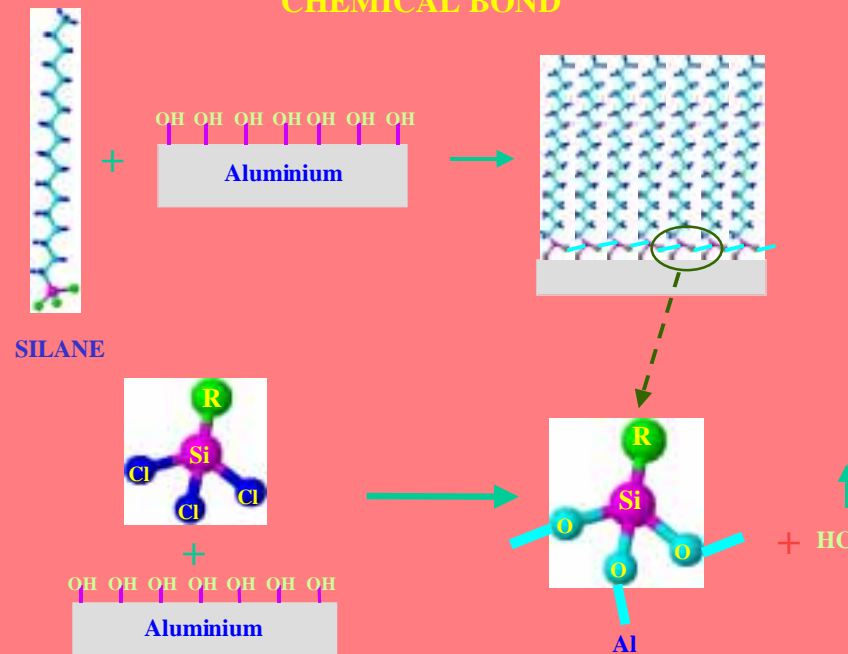


Bioelectronic devices

DNA SAMs



## CHEMICAL BOND



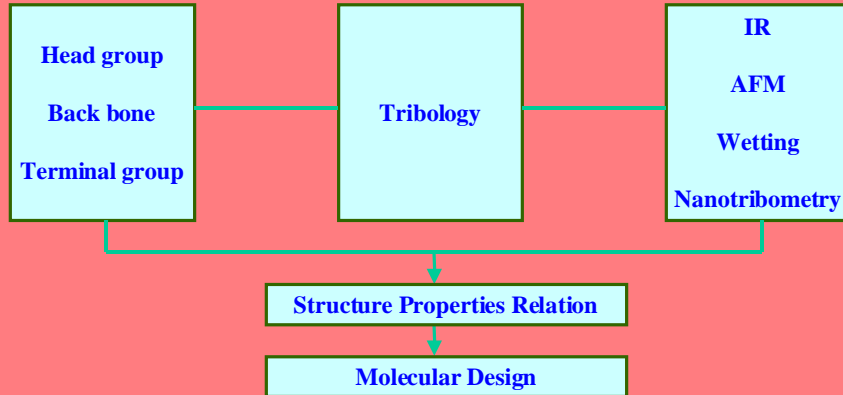
## Methodology

**Design of additive molecules for aluminium Tribology**

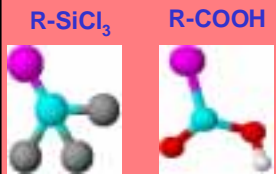
Approach: Find the relation of molecular structure with Tribology

Variation of Molecule structures

Analysis of Tribological mechanism



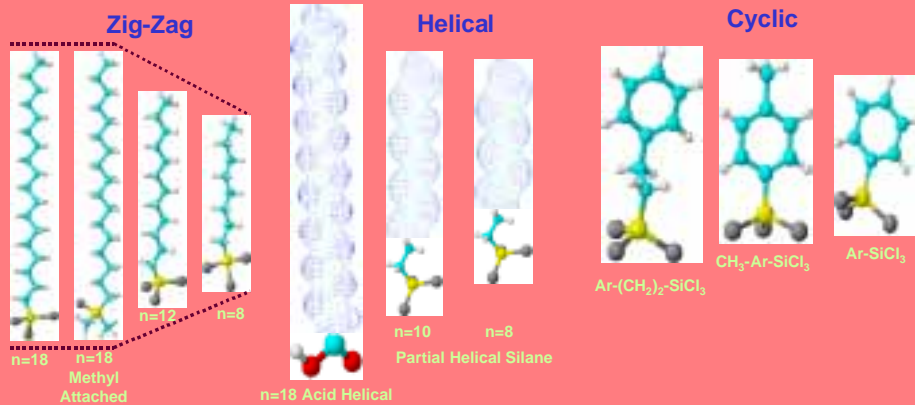
### > Head Group

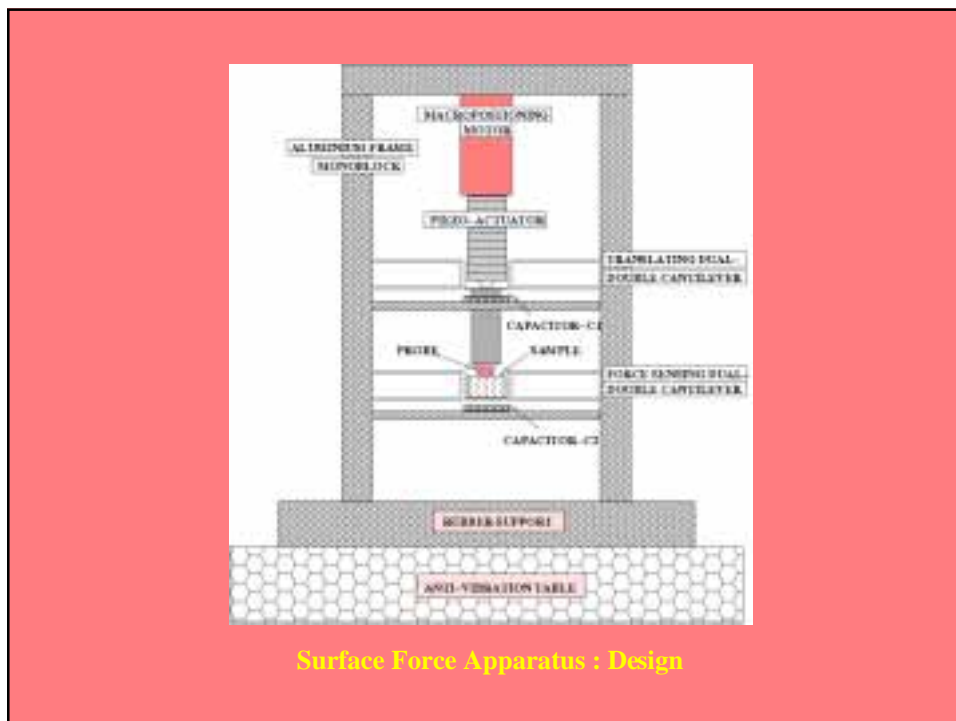
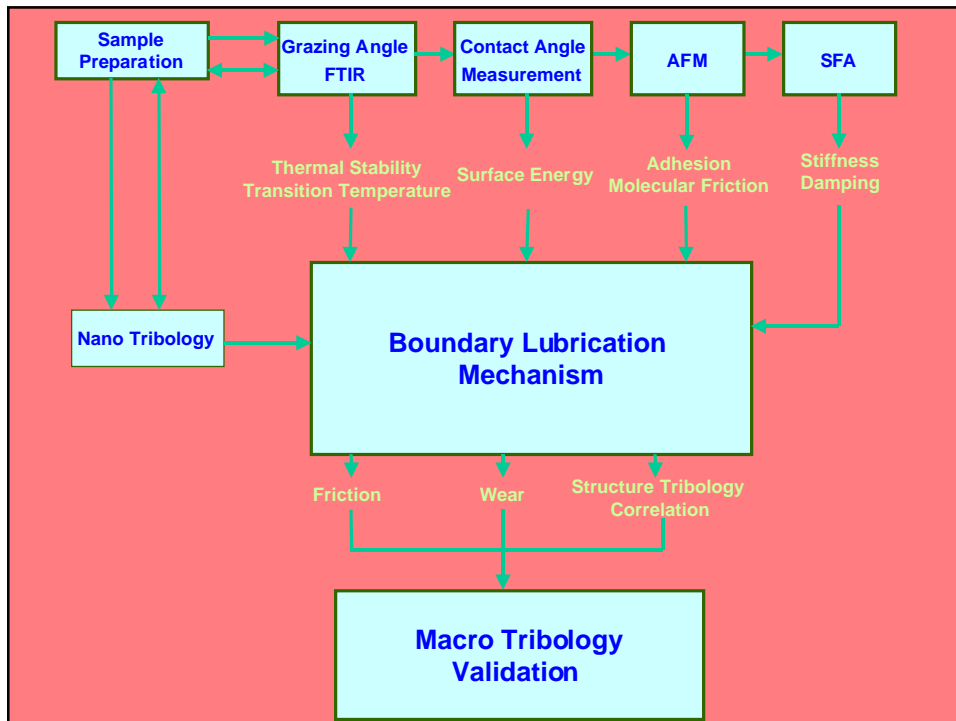


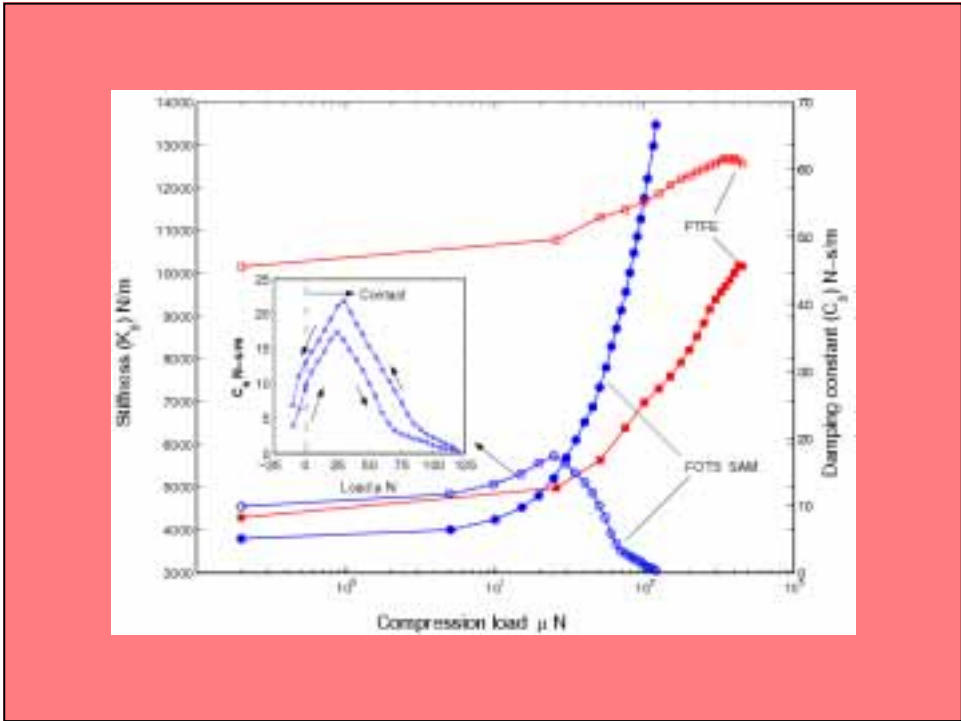
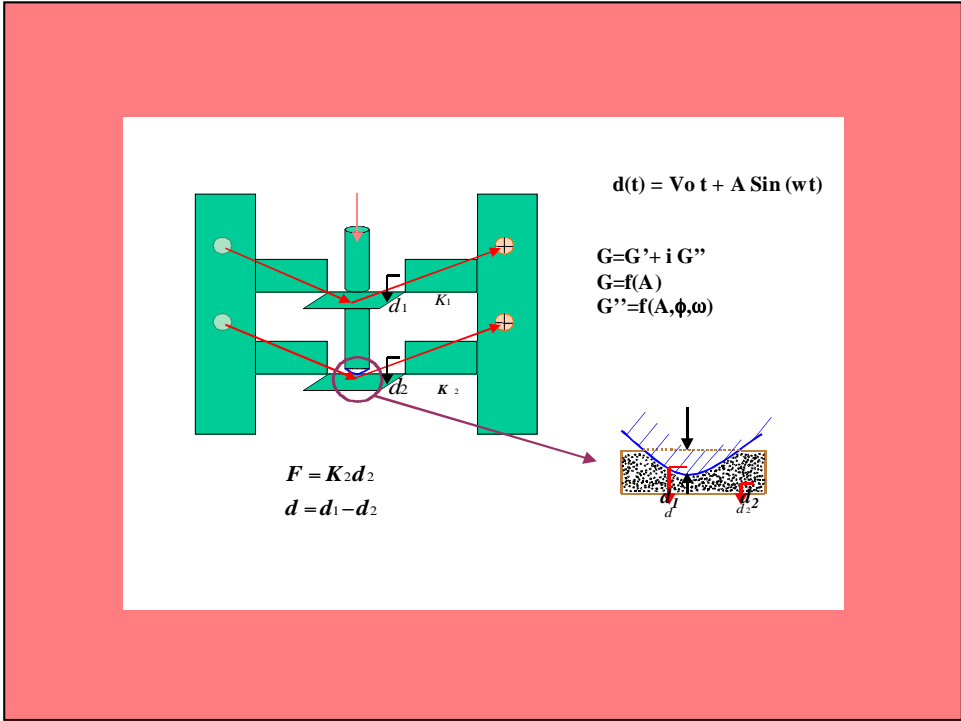
### > Terminal Group

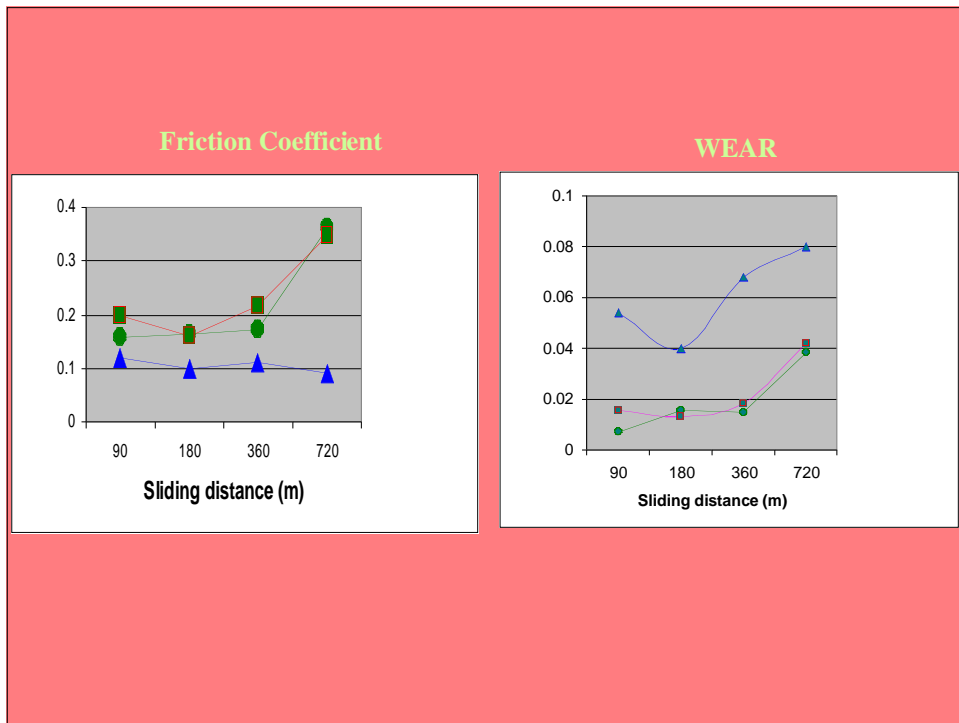
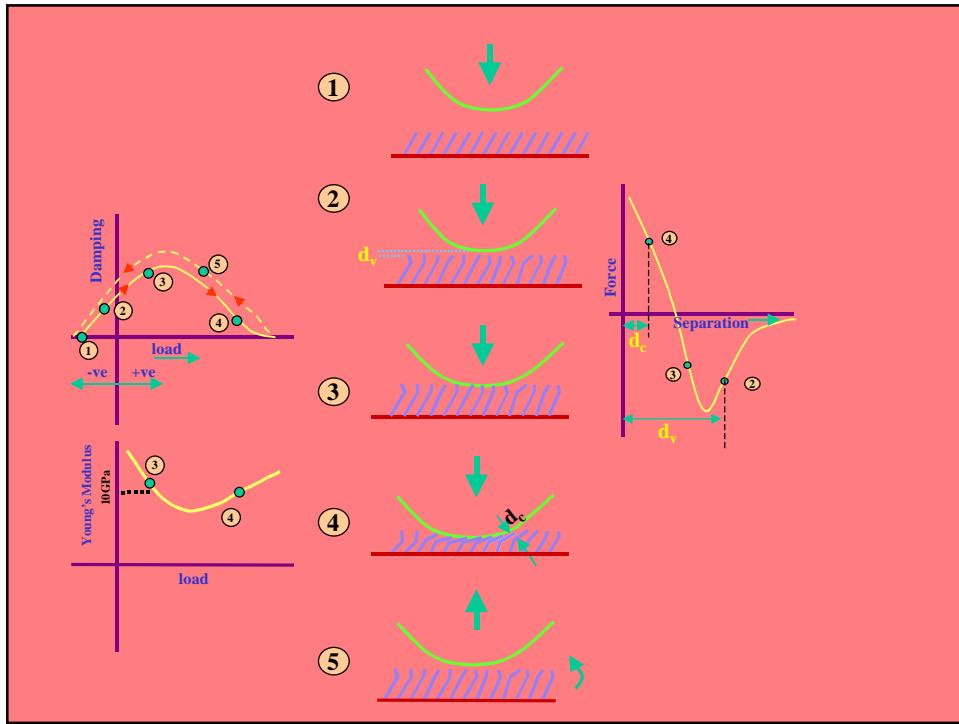


### > Back Bone









# The Nature of Contact Induced Deformation and Fracture in TiN Films on Steel

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*Indian Institute of Science*

Sanjith Bhowmick  
S.J. Suresha

*Indian Institute of Science  
India*

Dr. Mark Hoffman  
Z -H. Xie

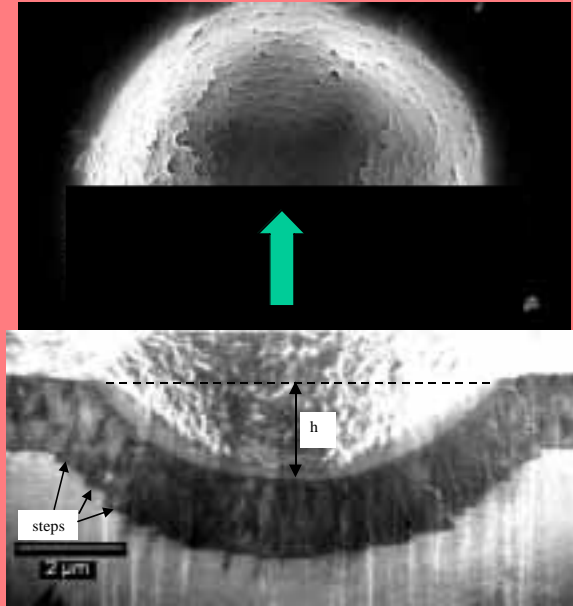
*University of New South Wales  
Australia*

Material detail



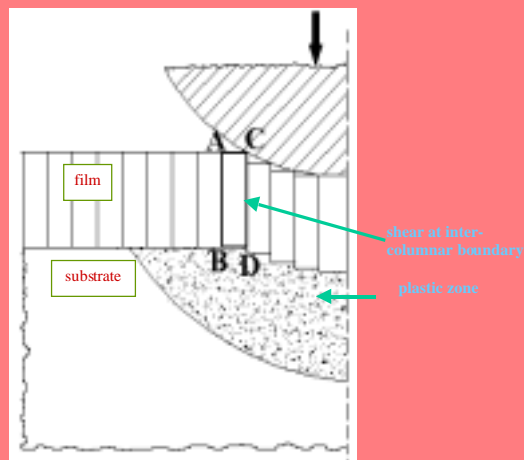
### Cross section view

Thin film on SS



A model on coating damage

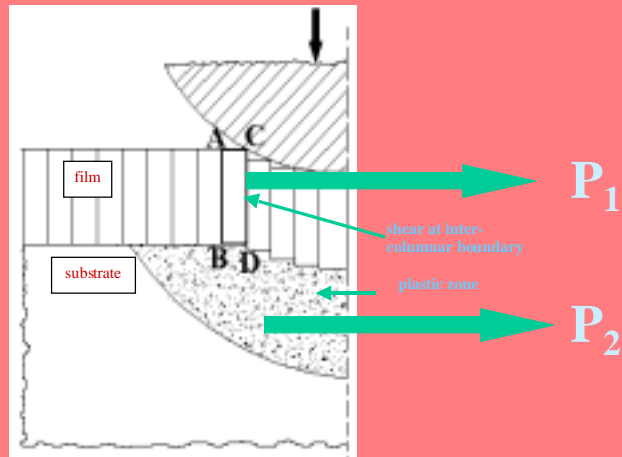
### At high loads



Schematic of the partitioning of load between the TiN annulus, ABCD, and the expanding cavity in the steel substrate.

A model on coating damage

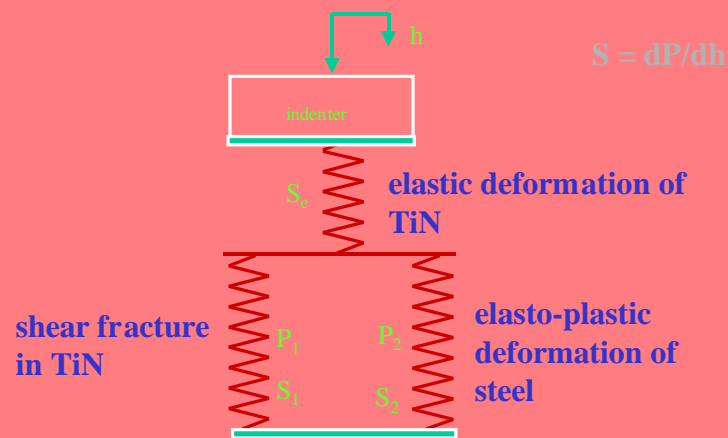
At high loads



Schematic of the partitioning of load between the TiN annulus, ABCD, and the expanding cavity in the steel substrate.

A model on coating damage

A spring-model to estimate entire loading part



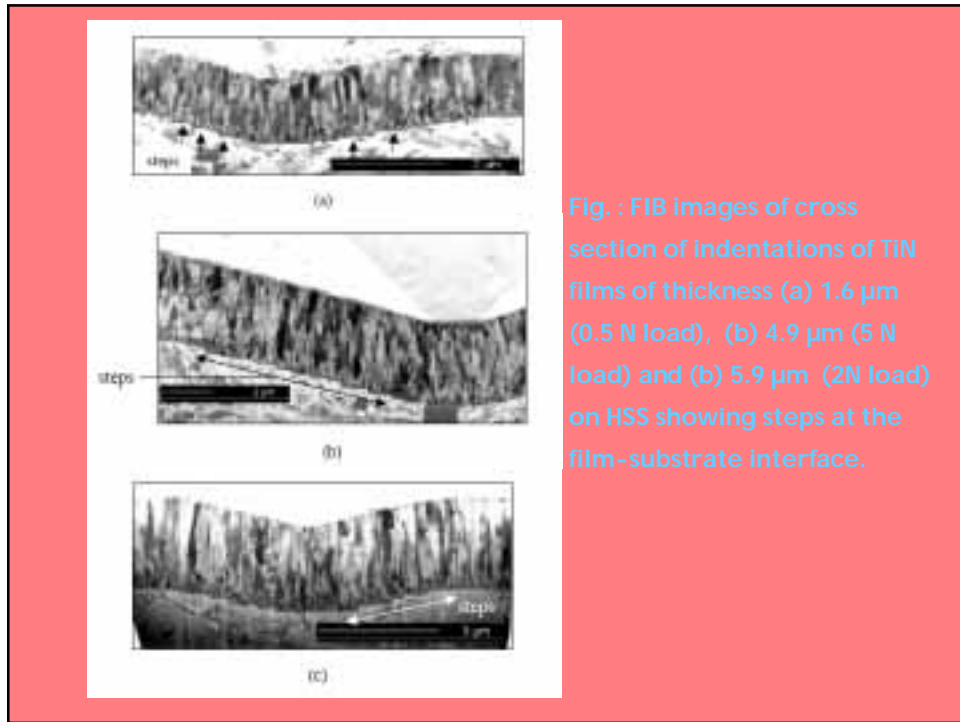


Fig. : FIB images of cross section of indentations of TIN films of thickness (a) 1.6  $\mu\text{m}$  (0.5 N load), (b) 4.9  $\mu\text{m}$  (5 N load) and (c) 5.9  $\mu\text{m}$  (2N load) on HSS showing steps at the film-substrate interface.

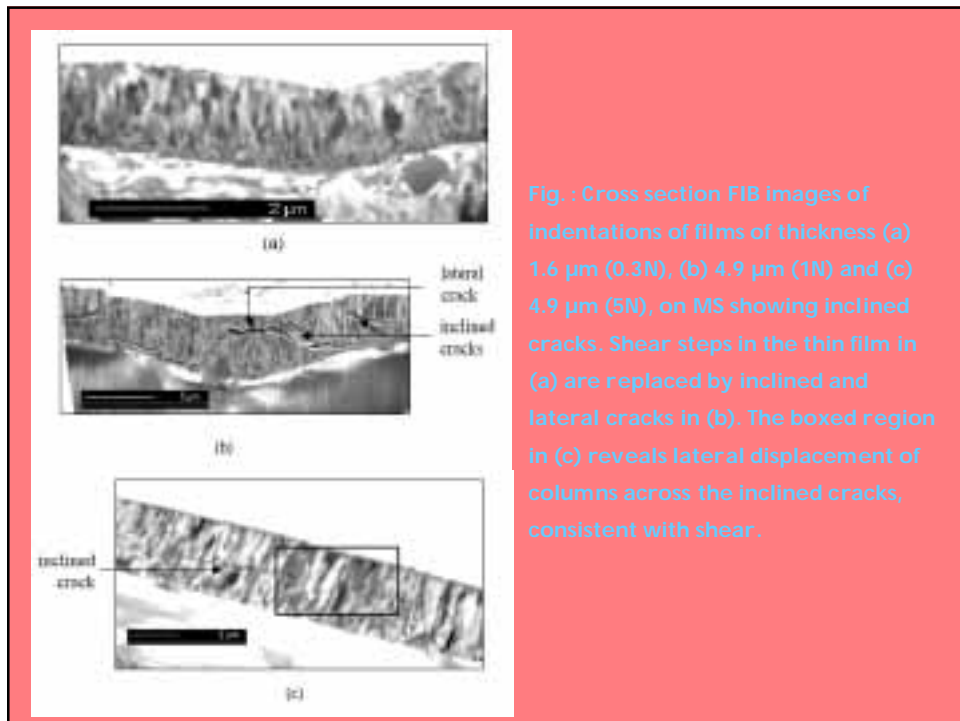


Fig. : Cross section FIB images of indentations of films of thickness (a) 1.6  $\mu\text{m}$  (0.3N), (b) 4.9  $\mu\text{m}$  (1N) and (c) 4.9  $\mu\text{m}$  (5N), on MS showing inclined cracks. Shear steps in the thin film in (a) are replaced by inclined and lateral cracks in (b). The boxed region in (c) reveals lateral displacement of columns across the inclined cracks, consistent with shear.



Fig. : Cross section FIB images of TiN films on Al: (a) 1.6  $\mu\text{m}$  film (0.3 N) showing array of inclined cracks near the inter- face, (b) 4.9  $\mu\text{m}$  film (1 N) displaying inclined cracks and lateral cracks under indentation.

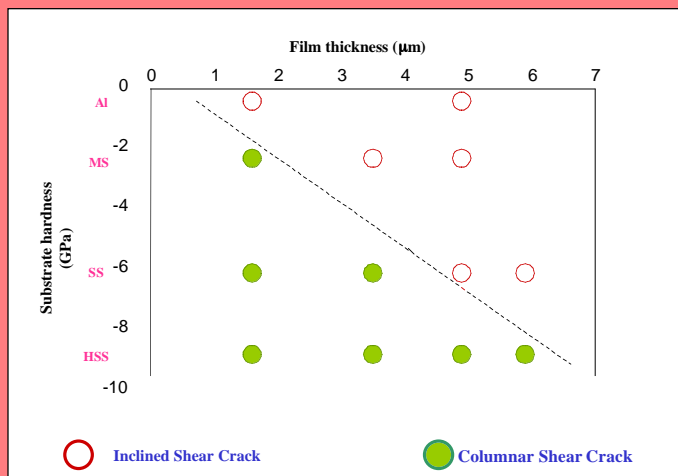
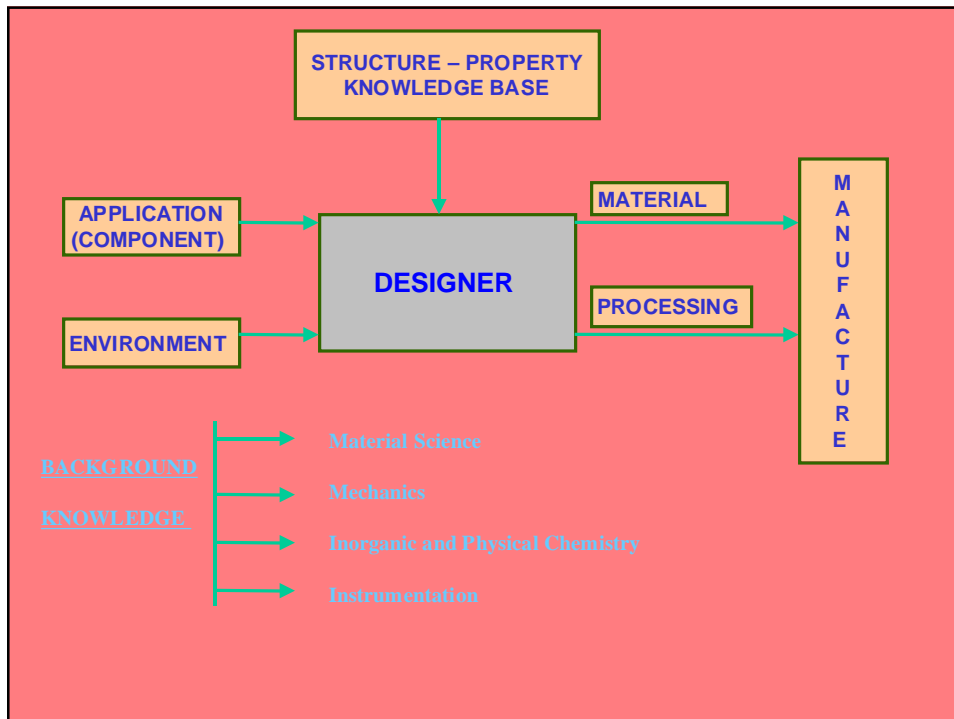


Fig. : A schematic diagram showing the change in failure modes with film thickness and substrate yield stress.

## THIN FILM FOR CHEMICAL AND MECHANICAL PROTECTION

THICKNESS	—	1nm (10 <sup>-9</sup> )	→	100_μm (10 <sup>-4</sup> m)
APPLICATION	—	MECHANICAL MACHINERY HUMAN JOINTS (BIOLOGICAL) ELECTRONIC (PACKAGING, DISK)		
PROTECTION FROM	—	MECHANICAL DAMAGE IN POWER TRANSMISSION, CHEMICAL ATTACK		
MATERIALS	—	ORGANIC MOLECULES ↓ HARD CERAMIC		
PROCESSING	—	SELF ASSEMBLY SPUTTERING PVD HIGH ENERGY ION BEAM ↓		
PROPERTIES	—	STIFFNESS / HARDNESS DAMPING FRICTION / WEAR THERMAL STABILITY		



<b>INTRODUCTION TO NANOTECHNOLOGY</b>												
<b>UNDERGRADUATE</b>												
<p><u>Pre requisite</u></p> <p><u>12<sup>th</sup> Standard</u>            Physics            Chemistry            Mathematics            Biology</p>	<p>❖ <u>Nanoscale S&amp;T Implication for Physics and Engineering for Chemistry and Biology</u></p> <p>Nano structured materials            Nano particles            Quantum Dots            Ultrathin films – Multilayers            Molecular Self Assembly</p> <table border="0"> <tr> <td style="padding-right: 20px;">Properties</td> <td>Mechanical</td> </tr> <tr> <td></td> <td>Electronic</td> </tr> <tr> <td></td> <td>Optical</td> </tr> <tr> <td></td> <td>Magnetic</td> </tr> <tr> <td></td> <td>Thermal</td> </tr> </table>	Properties	Mechanical		Electronic		Optical		Magnetic		Thermal	<p><u>5<sup>th</sup> Semester</u>            (50 Hours Inc. Lab)</p> <p><u>Compulsory</u></p>
Properties	Mechanical											
	Electronic											
	Optical											
	Magnetic											
	Thermal											

<p>❖ <u>Preparation Routes</u></p> <p>Precipitation            Milling            Colloidal Assembly            Vapour Phase Deposition            Molecular and Atomic epitaxy etc.            Lithography</p> <p>❖ <u>Preparation Environments</u></p> <p>Clean Rooms            Vibration            Working Practices</p> <p>❖ <u>Characterisation Techniques</u></p> <p>Diffraction            Spectroscopy            Electron Microscopy            SPM</p>	
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## MSc in Nanoelectronics and Nanomechanics (2 Semester)

### Semester 1

Generic methodologies for nanotechnology	(15 credits)
Semiconductor Nanotechnology	(15 credits)
Nanoscale Magnetic Materials and Devices	(15 credits)
Next generation silicon technologies	(15 credits)

### Semester 2

Microfluidics	(15 credits)
Micro-and nano-electromechanical systems	(15 credits)
Electronic and Photonic Molecular Materials and Devices	(15 credits)
Molecular Electronics	(15 credits)
Quantum Computing	(15 credits)

## PROBLEMS OF AN INTERDISCIPLINARY MASTERS COURSE IN NANOTECHNOLOGY

\* Diversity  
Prerequisites  
Flexibility

\* TEACHERS TRAINING

\* LABORATORY INFRASTRUCTURE  
DIVERSE  
EXPENSIVE  
NO PREVIOUS EXPOSURE

\* AVAILABILITY OF SCIENCE  
BASED INDUSTRIAL EMPLOYMENT

